



# EM Microelectronic

A COMPANY OF THE  SWATCH GROUP

## EM4200

### Product Presentation

*Backward compatibility with  
EM410x read only chips*



# EM4200 – Main Features

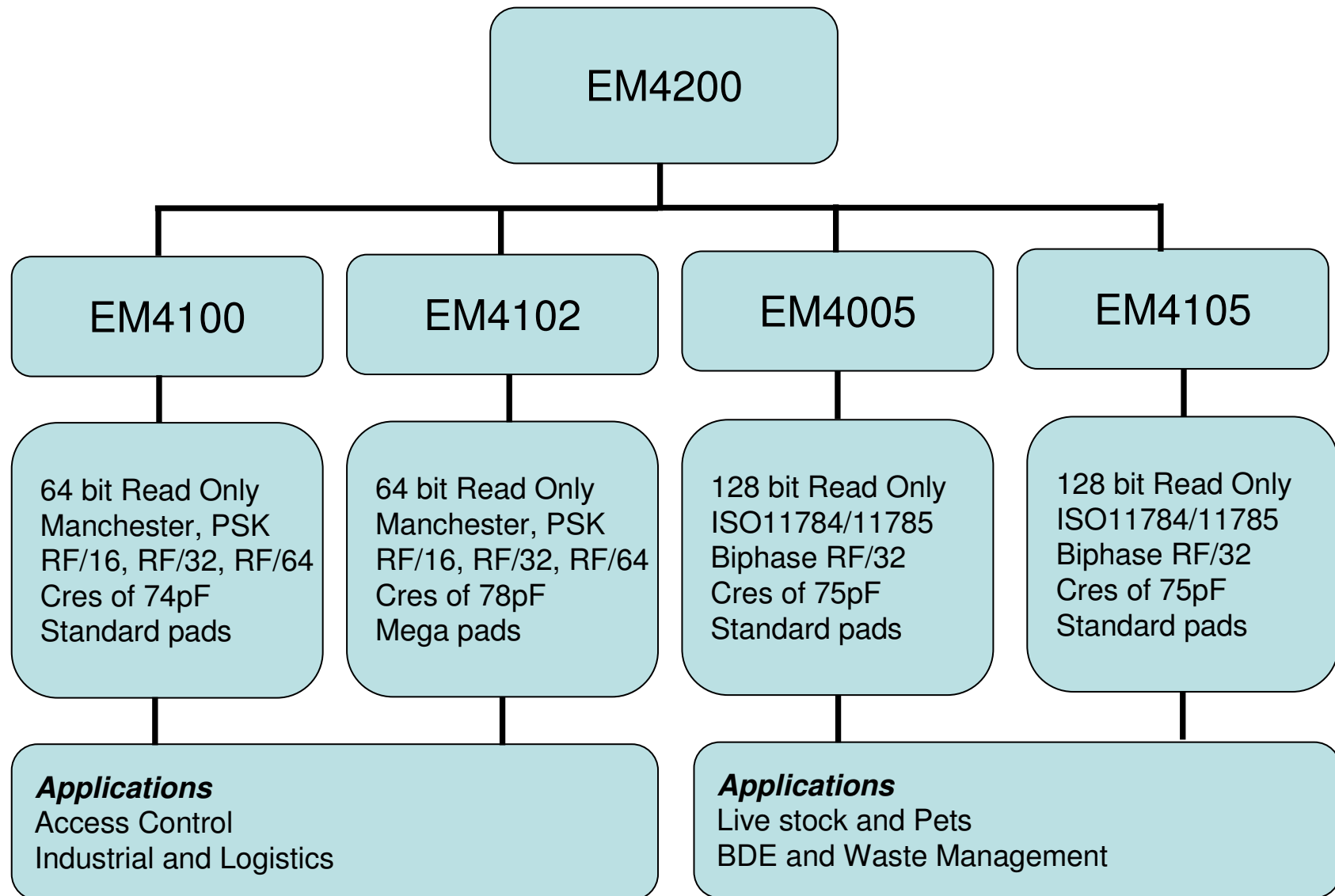
- ❖ Latest generation of low frequency read only chip
  - Direct successor of existing EM4100, EM4102, EM4005 and EM4105 ICs
  - Improved reading range performances, robust solution
  - Backward compliant with existing installed bases (all communication protocols supported)
  
- ❖ 128 bit ROM factory programmed, 2 \* 64 bit or 1 \* 128 bit serial number format
  
- ❖ Advanced serial number data base management to ensure uniqueness over EM4x0x chip generations

# EM4200 – Main Features

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- ❖ Mega bumps version available for flip chip process assembly
  
- ❖ Several options for the resonant capacitor
  - 75pF, 210pF and 250pF
  - Compatibility with other EM Marin LF chips (EM4205 and EM4305)

# EM4200 – One single chip replacing 4 existing ones



# EM4200 - Compatibility

## ❖ *Data Structure*

- 2 \* 64 bits EM4100/EM4102 data telegram composed by:
  - ❖ 9 bits header – Start bit “0”
  - ❖ 8 bit customer code
  - ❖ 32 bit data field
  - ❖ Column and Row Parity bit
- 1 \* 128 bit of EM4005/EM4105
  - ❖ ISO11784/11785
  - ❖ BDE telegram structure

❖ *Data encodings:* Manchester, Biphase, PSK

❖ *Data Rates:* RF/16, RF/32, RF/64

❖ *Resonant Capacitor:* 75pF

## EM4200 – Added Key features

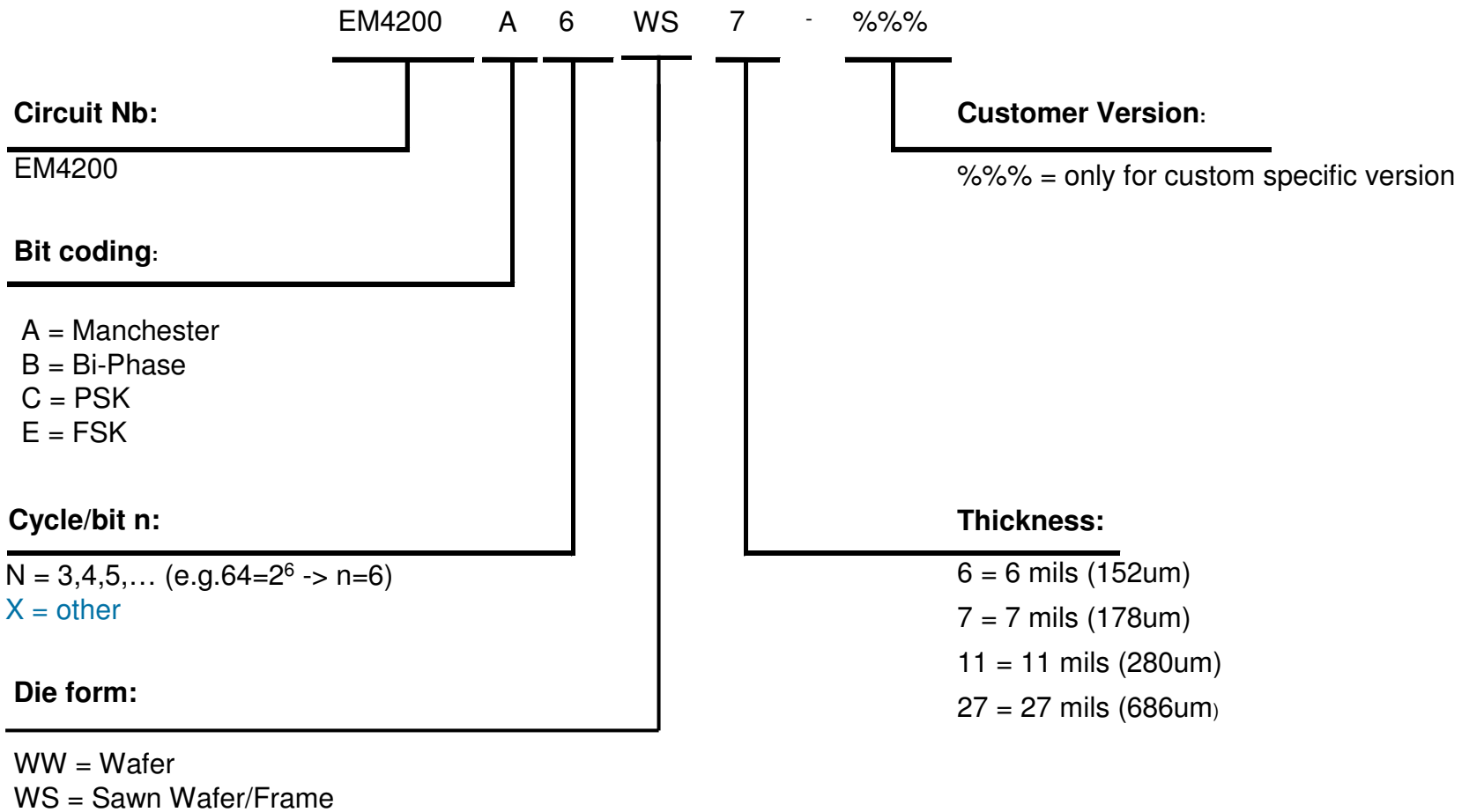
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- ❖ Higher resonant capacitor versions (210pF and 250pF) for tag miniaturization and process optimization
- ❖ Improved reading range on sensitive readers (~10% more). Transparent behavior on other readers and installed bases
- ❖ FSK2 data encoding supported
- ❖ Small die size, around 70k parts per 8 inch wafer
- ❖ Minimum ordering quantity of 2 wafers (~140k parts)
- ❖ New thin plastic package designed for manual or thermo compression soldering processes: EMDFN02

# EM4200 – Electrical Parameters Comparison

Parameters	Symbol	EM4200	EM4100	EM4102	EM4005	EM4105
<b>Input current on COIL1/COIL2</b>	I <sub>COIL</sub>	-30 to +30mA	-30 to +30mA	-30 to +30mA	-30 to +30mA	-30 to +30mA
<b>Operating temperature range</b>	T <sub>OP</sub>	-40 to +85°C	-40 to +85°C	-40 to +85°C	-40 to +85°C	-40 to +85°C
<b>Storage temperature range</b>	T <sub>STORE</sub>	-55 to +200°C	-55 to +200°C	-55 to +200°C	-55 to +200°C	-55 to +200°C
<b>Electrostatic discharge to MIL-STD-883 method 3015 Between Coil1 and Coil2</b>	V <sub>ESD</sub>	2000V	1000V	2000V	1000V	1000V
<b>Maximum coil current</b>	I <sub>COIL1</sub>	+/- 10mA	+/- 10mA	+/- 10mA	+/- 10mA	+/- 10mA
<b>Frequency on coil pads</b>	F <sub>COIL1</sub>	100kHz – 150kHz	100kHz – 150kHz	100kHz – 150kHz	100kHz – 150kHz	100kHz – 150kHz
<b>Limiter Voltage</b>	V <sub>LIM</sub>	8.2V Typ	7V Typ	7V Typ	7V Typ	7V Typ
<b>Resonant Capacitors</b>	C <sub>R</sub>	75pF +/-10%	74pF +/-15%	78pF +/-15%	75pF +/-15%	75pF +/-15%
<b>Modulation index range in ASK mode</b>	M <sub>r</sub>	41 - 73%	40 - 64%	35 - 62%	36 - 56%	36 - 56%

# EM4200 – Wafer form versions





# EM4200 – Package versions

EM4200 A 6 DF2 C - %%%

**Circuit Nb:**

EM4200

**Bit coding:**

- A = Manchester
- B = Bi-Phase
- C = PSK
- E = FSK

**Cycle/bit n:**

N = 3,4,5,... (e.g.64 = 2<sup>6</sup> -> n = 6)  
 X = other

**Package:**

DF2 = EMDFN02

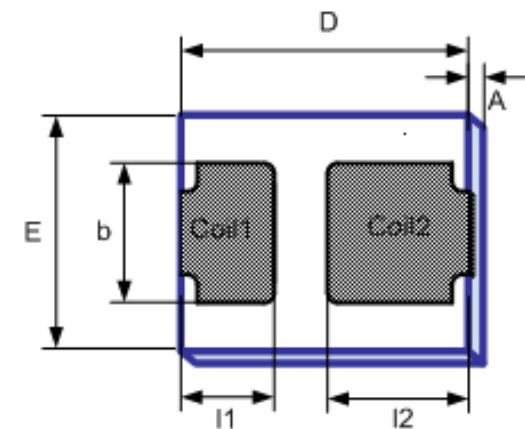
**Customer Version:**

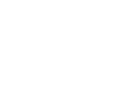
**Delivery form:**

C=Bulk (vrac)  
 H=Wafer frame

**Package mechanical dimensions:**

	A	D	E	B	I1	I2
<b>Size</b>	0.76	2.20	1.78	1.07	0.71	1.08
<b>Tolerance</b>	0.10	0.15	0.15	0.05	0.05	0.05





Thank you for your confidence